CMOSIC

8-bit Microcontroller with USB-host Controller

64K-byte Flash ROM / 8K-byte RAM / 48-pin

Overview

The LC87F1K64A is an 8-bit microcontroller that, integrates on a single chip a number of hardware features such as 64K-byte flash ROM, 8192-byte RAM, an on-chip debugger, a sophisticated 16-bit timer/counter (may be divided into 8-bit timers), a 16-bit timer (may be divided into 8-bit timers or PWMs), four 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, two channels of synchronous SIO interface with automatic data transfer capabilities, an asynchronous/synchronous SIO interface, a single-master I²C/synchronous SIO interface, a UART interface (full duplex), a full/low-speed USB interface (host control function) × 2 ports, a 12-bit 12-channel AD converter, two channels of 12-bit PWM, a system clock frequency divider, an infrared remote control receiver circuit, an internal reset circuit, and a 44-source 10-vector interrupt feature.

Features

- Flash ROM
 - 65536×8 bits
 - · Capable of on-board programming with a wide range of supply voltage from 3.0 to 5.5V
 - Block-erasable in 128-byte units
 - Data written in 2-byte units

RAM

- 8192×9 bits
- ■Package Form
 - SQFP48 (7×7): Lead-/halogen-free product

■Bus Cycle Time

- 83.3ns (when CF=12MHz)
 - Note: The bus cycle time here refers to the ROM read speed.
- ■Minimum Instruction Cycle Time (tCYC) • 250ns (when CF=12MHz)
- 9.0 7.0 Ӑ҄ѦѦѦѦѦѦѦѦѦҎ 37 24 7.0 9.0 12 ٥ 5 0.18 0.15 (0.75) 1000000000000 SQFP48(7X7)

ORDERING INFORMATION

See detailed ordering and shipping information on page 35 of this data sheet.

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SQFP48(7X7)





Ports

• I/O ports

Ports whose input/output can be specified in 1-bit units:	34 (P00 to P07, P10 to P17, P20 to P25, P30 to P34,
	P70 to P73, PWM0, PWM1, XT2)
• USB ports	4 (UHAD+, UHAD–, UHBD+, UHBD–)
 Dedicated oscillator ports 	2 (CF1, CF2)
• Input-only port (also used for the oscillator)	1 (XT1)
• Reset pin	$1 (\overline{\text{RES}})$
• Power supply pins	6 (V _{SS} 1 to 3, V _{DD} 1 to 3)
Timers	

- Timer 0: 16-bit timer/counter with 2 capture registers
 - Mode 0: 8-bit timer with an 8-bit programmable prescaler
 - (with two 8-bit capture registers) \times 2 channels
 - Mode 1: 8-bit timer with an 8-bit programmable prescaler
 - (with two 8-bit capture registers) + 8-bit counter (with two 8-bit capture registers)
 - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with two 16-bit capture registers)
 - Mode 3: 16-bit counter (with two 16-bit capture registers)
- Timer 1: 16-bit timer/counter that supports PWM/toggle output
 - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle output)
 - + 8-bit timer/counter with an 8-bit prescaler (with toggle output)
 - Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels
 - Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle output)
 - (Toggle output also possible from low-order 8 bits.)
 - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle output)
 - (Low-order 8 bits can be used as a PWM output.)
- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base timer

1) The clock can be selected from among a subclock (32.768kHz crystal oscillator), low-speed RC oscillator clock, system clock, and timer 0 prescaler output.

2) Interrupts programmable in 5 different time schemes.

■Serial Interfaces

- SIO0: Synchronous serial interface
 - 1) LSB first/MSB first selectable
 - 2) Transfer clock cycle: 4/3 to 512/3 tCYC
 - Continuous automatic data transmission (1 to 256 bits can be specified in 1-bit units) (Suspension and resumption of data transfer possible in 1-byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
- Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clock) Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrate) Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clock)
- Mode 3: Bus mode 2 (start detection, 8 data bits, stop detection)
- SIO4: Synchronous serial interface
- 1) LSB first/MSB first selectable
- 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
- 3) Continuous automatic data transmission (1 to 8192 bytes can be specified in 1-byte units) (Suspension and resumption of data transmission possible in 1-byte units or in word units)
- 4) Clock polarity can be selected.
- 5) CRC16 calculator circuit built- in
- SMIIC0: Single-master I²C/8-bit synchronous SIO Mode 0: Communication in single-master mode. Mode 1: 8-bit synchronous serial I/O (data MSB first)

- ■Full Duplex UART
 - 1) Data length: 7/8/9 bits selectable
 - 2) Stop bits: 1 bit (2 bits in continuous transmission mode)
 - 3) Parity bits: None/even/odd selectable (for 8-bit data only)
 - 4) Baudrate: 16/3 to 8192/3 tCYC
- AD Converter: 12 bits × 12 channels
- ■PWM: Variable frequency 12-bit PWM × 2 channels
- Infrared Remote Control Receiver Circuit
 - 1) Noise rejection function (noise filter time constant: Approx. 120us when the 32.768kHz crystal oscillator is selected as the reference clock)
 - 2) Supports data encoding systems such as PPM (Pulse Position Modulation) and Manchester encoding.
 - 3) X'tal HOLD mode release function
- ■USB Interface (host control function) × 2 ports
 - 1) Supports full-speed (12Mbps) and low-speed (1.5Mbps) specifications.
 - 2) Supports four transfer types (control transfer, bulk transfer, interrupt transfer, and isochronous transfer).
- Audio Interface
 - 1) Sampling frequencies (fs): 8kHz/11.025kHz/12kHz/16kHz/22.05kHz/24kHz/32kHz/44.1kHz/48kHz
 - 2) Master clock: 256fs/384fs 48fs/64fs
 - 3) Bit clock:
 - 4) Data bit length: 16bits/18bits/20bits/24bits
 - 5) LSB first/MSB first selectable.
 - 6) Left justified/right justified/I2S format selectable
- ■Watchdog Timer
 - External RC time constant type
 - 1) Interrupt generation/reset generation selectable
 - 2) Operation in HALT/HOLD mode can be selected from "continue operation" and "suspend operation."
 - Internal timer type
 - 1) Capable of generating a internal reset signal on an overflow of the timer running on the low-speed RC oscillator clock, or subclock.
 - 2) Operation in HALT/HOLD mode can be selected from among "continue count operation," "suspend operation," and "retain the count value."

■Clock Output Function

- 1) Can output a clock with a clock rate of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 of the source oscillator clock selected as the system clock.
- 2) Can output the source oscillator clock for the subclock.

Interrupts

- 44 sources, 10 vectors
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt request of the level equal to or lower than the current interrupt level is not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the lowest vector address is given priority.

No.	Vector	Level	Interrupt Source
1	00003H	X or L	INTO
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/UHC-A bus active/UHC-B bus active/remote control receive
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	T0H/INT6/UHC-A device connected, disconnected, resumed
6	0002BH	H or L	T1L/T1H/INT7/AIF start/SMIIC0/UHC-B device connected, disconnected, resumed
7	00033H	H or L	SIO0/UART1 reception completed
8	0003BH	H or L	SIO1/SIO4/UART1 buffer empty/UART1 transmission completed/AIF end
9	00043H	H or L	ADC/T6/T7/UHC-ACK/UHC-NAK/UHC error/UHC-STALL
10	0004BH	H or L	Port 0/PWM0/PWM1/T4/T5/UHC-SOF

- Priority levels X > H > L
- When interrupts of the same level occur at the same time, the interrupt with the lowest vector address is given priority.

■ Subroutine Stack Levels: Up to 4096 levels (The stack is allocated in RAM.)

■ High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits ÷ 16 bits (12 tCYC execution time)

■Oscillator Circuit and PLL

- Medium-speed RC oscillator circuit (internal): For system clock (approx. 1MHz)
- Low-speed RC oscillator circuit (internal): For system clock, timer, and watchdog timer (approx. 30kHz)
- CF oscillator circuit:
- Crystal oscillator circuit:
- PLL circuit (internal):

- For system clock For system clock and time-of-day clock
- For USB interface (see Fig. 5) and audio interface (see Fig. 6)

■Internal Reset Functions

- Power-on reset (POR) function
 - 1) POR is activated at power-on.
 - 2) POR release voltage can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) by setting options.
- Low voltage detection reset (LVD) function
- 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a threshold level.
- 2) The use/disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, and 4.28V) can be selected by setting options.

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillators do not stop automatically.
 - 2) There are three ways of releasing HOLD mode.
 - (1) Setting the reset pin to a low level.
 - (2) Generating a reset signal by watchdog timer or low-voltage detection
 - (3) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and operation of the peripheral circuits.
 - 1) The PLL, CF, RC and crystal oscillators automatically stop operation.
 - Note: Low-speed RC oscillator is controlled directly by the watchdog timer and its oscillation in standby mode is also controlled.
 - 2) There are five ways of releasing HOLD mode.
 - (1) Setting the reset pin to a low level
 - (2) Generating a reset signal by the watchdog timer or low-voltage detection
 - (3) Establishing an interrupt source at one of INT0, INT1, INT2, INT4, and INT5 pins
 - * INT0 and INT1 HOLD mode release is available only when level detection is configured.
 - (4) Establishing an interrupt source at port 0
 - (5) Establishing an bus active interrupt source in the USB host control circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer and infrared remote control receiver circuit.
 - 1) The PLL, CF and RC oscillators automatically stop operation.
 - Note: Low-speed RC oscillator is controlled directly by the watchdog timer and its oscillation in standby mode is also controlled.
 - Note: The low-speed RC oscillator retains the state that is established on entry into X'tal HOLD mode if the base timer is running with the low-speed RC oscillator selected as the base timer input clock source.
 - 2) The state of crystal oscillator established when the X'tal HOLD mode is entered is retained.
 - 3) There are seven ways of releasing X'tal HOLD mode.
 - (1) Setting the reset pin to a low level
 - (2) Generating a reset signal by the watchdog timer or low-voltage detection
 - (3) Establishing an interrupt source at one of INT0, INT1, INT2, INT4, and INT5 pins
 - * INT0 and INT1 X'tal HOLD mode release is available only when level detection is configured.
 - (4) Establishing an interrupt source at port 0
 - (5) Establishing an interrupt source in the base timer circuit
 - (6) Establishing an interrupt source in the infrared remote control receiver circuit
 - (7) Establishing an bus active interrupt source in the USB host control circuit
- Development Tools
 - On-chip debugger: TCB87–Type B + LC87F1K64A or

TCB87-Type C (3-wire communication cable) + LC87F1K64A

■Flash ROM Programming Board

Package	Programming Board
SQFP48 (7×7)	W87F55256SQ

Maker		Model	Supported Version	Device
Flash Support Group Company (FSG)		AF9709C Rev.03.32 and later		87F064JU
Flash Support Group		AF9101/AF9103 (main unit)		
Company (FSG)	Onboard	(FSG model)	(Nata 2)	LC87F1K64A
+	single/ganged	SIB87 Type C (interface driver)	(Note 2)	
Our company (Note 1)		(Our company model)		
	Cinale (new red	SKK/SKK Type C	Application version	
0	Single/ganged	(SANYO FWS)	1.07 and later	
Our company	Onboard	SKK-DBG Type C	Chip data version	LC87F1K6
	single/ganged	(SANYO FWS)	2.39 and later	

(Further information on the AF series) Flash Support Group Company (TOA ELECTRONICS, Inc.) Phone: 053-459-1050 E-mail: sales@j- fsg.co.jp

Note 1: PC-less standalone onboard programming is possible using the FSG onboard programmer (AF9101/AF9103) and the serial interface driver (SIB87 Type C) provided by Our company in pair.

Note 2: Dedicated programming device and program are required depending on the programming conditions. Contact Our company or FSG if you have any questions or difficulties regarding this matter.

Package Dimensions

unit : mm (typ) 3163B



Pin Assignment



SQFP48 (7×7) (Lead-/halogen-free product)

SQFP48	NAME
1	P73/INT3/T0IN/RMIN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V _{SS} 1
6	CF1
7	CF2
8	V _{DD} 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1/SM0CK1
13	P14/SI1/SB1/SM0DA1
14	P15/SCK1/SM0DO
15	P16/T1PWML/SM0DA0
16	P17/T1PWMH/BUZ/SM0CK0
17	PWM1/MCLKI
18	PWM0/MCLKO
19	V _{DD} 2
20	V _{SS} 2
21	P00/AN0
22	P01/AN1
23	P02/AN2/DBGP0
24	P03/AN3/DBGP1

SQFP48	NAME
25	P04/AN4/DBGP2
26	P05/AN5/CKO/SDAT
27	P06/AN6/T6O/BCLK
28	P07/AN7/T7O/LRCK
29	P20/INT4/INT6
30	P21/INT4
31	P22/INT4/SO4
32	P23/INT4/SI4
33	P24/INT5/INT7/SCK4
34	P25/INT5
35	UHBD-
36	UHBD+
37	UHAD-
38	UHAD+
39	V _{DD} 3
40	V _{SS} 3
41	P34/UFILT
42	P33/AFILT
43	P32
44	P31/URX1
45	P30/UTX1
46	P70/INT0/T0LCP/AN8
47	P71/INT1/T0HCP/AN9
48	P72/INT2/T0IN

System Block Diagram



Pin Description

Pin Name	I/O			C	Description			Option		
V _{SS} 1, V _{SS} 2, V _{SS} 3	-	-power supp	-power supply							
V _{DD} 1, V _{DD} 2	-	+power supp	+power supply							
V _{DD} 3	-	USB referen	ce voltage					Yes		
Port 0	I/O	• 8-bit I/O po	rt					Yes		
P00 to P07		 Pull-up resi HOLD relea Port 0 inter Pin functior AD convert On-chip de P05: Syster P06: Timer 	 I/O can be specified in 1-bit units Pull-up resistors can be turned on and off in 1-bit units. HOLD release input Port 0 interrupt input Pin functions AD converter input port: AN0 to AN7 (P00 to P07) On-chip debugger pins: DBGP0 to DBGP2 (P02 to P04) P05: System clock output / audio interface SDAT I/O P06: Timer 6 toggle output / audio interface BCLK I/O P07: Timer 7 toggle output / audio interface LRCK I/O 							
Port 1	I/O	• 8-bit I/O po	rt					Yes		
P10 to P17		Pull-up resi Pin function P10: SIO0 P11: SIO0 P12: SIO0 P13: SIO1 P14: SIO1 P15: SIO1	 I/O can be specified in 1-bit units Pull-up resistors can be turned on and off in 1-bit units. Pin functions P10: SIO0 data output P11: SIO0 data input / bus I/O P12: SIO0 clock I/O P13: SIO1 data output / SMIIC0 clock I/O P14: SIO1 data input / bus I/O / SMIIC0 bus I/O / data input P15: SIO1 clock I/O / SMIIC0 data output (used in 3-wire SIO mode) P16: Timer 1 PWML output / SMIIC0 bus I/O / data input							
Port 2	I/O							Yes		
P20 to P25		Pull-up resi Pin function P20 to P23 P24 to P25 P20: INT6 P22: SIO4 P23: SIO4 P24: INT7 Interrupt ac INT4 INT5 INT6	INT5 Enable Enable Enable Disable Disable							
		INT7	Enable	Enable	Enable	Disable	Disable			
Port 3 P30 to P34	I/O	I/O + 5-bit I/O port - I/O can be specified in 1-bit units - Pull-up resistors can be turned on and off in 1-bit units Pin functions P30: UART1 transmit						Yes		
		P31: UART								
		I P33 Conn	ected to audio in	tertace PLL filter	circuit (see Fig. 6)					

Continued on next page.

Continued fro	m precedi	ng page.							
Pin Name	I/O		Description						
Port 7	I/O	• 4-bit I/O por	t					No	
P70 to P73	1	• I/O can be specified in 1-bit units							
		Pull-up resistors can be turned on and off in 1-bit units.							
		Pin functions							
			•	•	r 0L capture input /				
			dog timer output						
			•	ease input / timei ease input / timei	OH capture input				
			•	/ high-speed clo					
				noise filter) / time					
				,	e control receiver ir	nput			
				8 (P70), AN9 (P					
		Interrupt acl	nowledge types						
			Rising	Falling	Rising & Falling	H Level	L Level		
		INT0	Enable	Enable	Disable	Enable	Enable		
		INT1	Enable	Enable	Disable	Enable	Enable		
		INT2	Enable	Enable	Enable	Disable	Disable		
		INT3	Enable	Enable	Enable	Disable	Disable		
PWM0	I/O	PWM0 and PWM1 output port					No		
PWM1		General-purpose input port Pin functions 							
				ster clock output					
			dio interface ma						
UHAD-	I/O	1		eral-purpose I/O	port			No	
UHAD+					•				
UHBD-	I/O	USB-B port d	ata I/O pin / ger	eral-purpose I/O	port			No	
UHBD+									
RES	I/O	External rese	t input / internal	reset output				No	
XT1	I	• 32.768kHz	crystal resonato	rinput				No	
		Pin function	S						
			General-purpose input port						
			er input port: AN						
XT2	I/O		crystal resonato	routput				No	
		Pin function							
			rpose I/O port	11					
CF1	1		er input port: AN tal resonator inp					No	
CF2	0	-						No	
UFZ	0	Ceramic/Crys	tal resonator ou	ipui				INU	

On-chip Debugger Pin Treatment

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 On-chip Debugger Installation Manual."

Recommended Unused Pin Treatment

Pin Name	Recommend	ed Unused Pin Treatment
Pin Name	Board	Software
P00 to P03, P05 to P07	Open	Set output low.
P04	Pull-down with a $100k\Omega$ resistor.	-
P10 to P17	Open	Set output low.
P20 to P25	Open	Set output low.
P30 to P34	Open	Set output low.
P70 to P73	Open	Set output low.
PWM0, PWM1	Open	Set output low.
UHAD+, UHAD-	Open	Set output low.
UHBD+, UHBD-	Open	Set output low.
XT1	Pull-down with a resistor of $100k\Omega$ or lower.	-
XT2	Open	Set output low.

Note: Since P34 is multiplexed with UFILT, it must be configured for input when the USB function is to be used.

Since P33 is multiplexed with AFILT, it must be configured for input when the audio interface PLL circuit is to be used.

Port Output Types

The table below lists the type of port output and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1 bit	1	CMOS	Programmable
P10 to P17		2	N-channel open drain	Programmable
P20 to P25				
P30 to P34				
P70	-	No	N-channel open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
UHAD+, UHAD-	-	No	CMOS	No
UHBD+, UHBD-				
XT1	-	No	Input only	No
XT2	-	No	32.768kHz crystal resonator output	No
			(N-channel open drain when in	
			general-purpose output mode)	

Option Name	Option to be Applied on	Flash-ROM Version	Option Selected in Units of	Option Selection
Port output type	D00 1. D07	0	4.5.1	CMOS
	P00 to P07	0	1 bit	N-channel open drain
		0		CMOS
	P10 to P17	0	1 bit	N-channel open drain
	D00 / D05	0		CMOS
	P20 to P25	0	1 bit	N-channel open drain
	D00 1: D04	0	4.1.11	CMOS
	P30 to P34	0	1 bit	N-channel open drain
Program start		0		00000h
address	-	0	-	0FE00h
USB regulator		0		Use
	USB regulator	0	-	Non-use
	USB regulator	0		Use
	(HOLD mode)	0	-	Non-use
	USB regulator	0		Use
	(HALT mode)	0	-	Non-use
Main clock 8MHz		0		Enable
selection	-	0	-	Disable
Low-voltage				Enable: Use
detection reset function	Detection function	0	-	Disable: Non-use
	Detection level	0	-	7 levels
Power-on reset function	Power-on reset level	0	-	8 levels

USB Reference Power Option

When a voltage 4.5 to 5.5V is supplied to V_{DD1} and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of the reference voltage circuit can be switched by selecting an option. The procedure for making the option selection is described below.

		(1)	(2)	(3)	(4)
	USB regulator	Use	Use	Use	Non-use
Option settings	USB regulator at HOLD mode	Use	Non-use	Non-use	Non-use
	USB regulator at HALT mode	Use	Non-use	Use	Non-use
Reference voltage circuit state	Normal mode	Active	Active	Active	Inactive
	HOLD mode	Active	Inactive	Inactive	Inactive
	HALT mode	Active	Inactive	Active	Inactive

• When the USB reference voltage circuit is made inactive, the level of the reference voltage for the USB port output is equal to V_{DD}1.

• Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.

• When the reference voltage circuit is activated, the current drain increases by approximately 100 μ A compared with when the reference voltage circuit is inactive.

Example 1: VDD1=VDD2=3.3V

- Inactivating the reference voltage circuit (selection (4)).
- Connecting $V_{DD}3$ to $V_{DD}1$ and $V_{DD}2$.



Example 2: VDD1=VDD2=5.0V

• Activating the reference voltage circuit (selection (1)).

• Isolating VDD3 from VDD1 and VDD2, and connecting capacitor between VDD3 and VSS.



	Parameter	Symbol	Pin/Remarks	Conditions			Specific	ation	
	Faidilletei	-	FIII/Remarks	Conditions	V _{DD} [V]	min	typ	max	uni
	ximum supply age	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		+6.5	
npı	ut voltage	V _I (1)	XT1, CF1, RES			-0.3		V _{DD} +0.3	v
•	ut/output age	V _{IO} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1 XT2			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1, 2	When CMOS output type is selected Per 1 applicable pin		-10			
		IOPH(2)	PWM0, PWM1	Per 1 applicable pin		-20			
		IOPH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-5			
irrent	Average output current (Note 1-1)	IOMH(1)	Ports 0, 1, 2	 When CMOS output type is selected Per 1 applicable pin 		-7.5			
ut cu		IOMH(2)	PWM0, PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-3			
High	Total output current	ΣIOAH(1)	Ports 0, 2	Total current of all applicable pins		-25			
		ΣIOAH(2)	Port 1 PWM0, PWM1	Total current of all applicable pins		-25			
		ΣIOAH(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins		-45			
		ΣIOAH(4)	Port 3 P71 to P73	Total current of all applicable pins		-10			
		ΣΙΟΑΗ(5)	UHAD+, UHAD- UHBD+, UHBD-	Total current of all applicable pins		-50			mA
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Ports 3, 7 XT2	Per 1 applicable pin				10	
ent	Average output current (Note 1-1)	IOML(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				15	
curr	(IOML(2)	P00, P01	Per 1 applicable pin				20	
Low level output current		IOML(3)	Ports 3, 7 XT2	Per 1 applicable pin				7.5	
ow leve	Total output current	ΣIOAL(1)	Ports 0, 2	Total current of all applicable pins				45	
		ΣIOAL(2)	Port 1 PWM0, PWM1	Total current of all applicable pins				45	
		ΣIOAL(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins				80	
		ΣIOAL(4)	Ports 3, 7 XT2	Total current of all applicable pins				15	
		ΣIOAL(5)	UHAD+, UHAD- UHBD+, UHBD-	Total current of all applicable pins				50	
	wable power sipation	Pd max	SQFP48(7×7)	Ta=-40 to +85°C				140	mV
	erating ambient nperature	Topr				-40		+85	°C
	rage ambient perature	Tstg				-55		+125	U

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Deservator	Oursehal	Dia (Descender	Oraditions			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	0.245µs ≤ tCYC ≤ 200µs		3.0		5.5	
supply voltage (Note 2-1)			0.245μs ≤ tCYC ≤ 0.383μs USB circuit active.		3.0		5.5	
			0.490µs ≤ tCYC ≤ 200µs Except for onboard programming mode		2.7		5.5	
Memory retention supply voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents are retained in HOLD mode		2.0		5.5	
High level input voltage	V _{IH} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1		2.7 to 5.5	0.3V _{DD} +0.7		V _{DD}	v
	V _{IH} (2)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V _{DD}		V _{DD}	
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3, 7		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
	V _{IL} (2)			2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 0 PWM0, PWM1		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
	V _{IL} (4)			2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (5)	XT1, XT2, CF1, RES		2.7 to 5.5	V _{SS}		0.25V _{DD}	
nstruction	tCYC			3.0 to 5.5	0.245		200	
cycle time			USB circuit active.	3.0 to 5.5	0.245		0.383	
(Note 2-2)			Except for onboard programming mode	2.7 to 5.5	0.490		200	μs
External system clock frequency	FEXCF(1)	CF1	 CF2 pin open System clock frequency division ratio =1/1 External system clock duty =50±5% 	3.0 to 5.5	0.1		12	MU
			 CF2 pin open System clock frequency division ratio =1/1 External system clock duty =50±5% 	2.7 to 5.5	0.1		6	MH
Oscillation frequency range (Note 2-3)	FmCF	CF1, CF2	12MHz ceramic oscillation mode See Fig. 1.	3.0 to 5.5		12		MH
	FmRC		Internal medium-speed RC oscillation	2.7 to 5.5	0.5	1.0	2.0	
	FmSRC		Internal low-speed RC oscillation	2.7 to 5.5	15	30	60	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation mode See Fig. 2.	2.7 to 5.5		32.768		kHz

Allowable Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 2-1: VDD must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Deremeter	Symbol	Din/Domorko	Conditions			Specifica	tion	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	uni
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3, 7 RES PWM0, PWM1	Output disabled Pull-up resistor off VIN ^{=V} DD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I _{IH} (2)	XT1, XT2	Input port configuration VIN=VDD	2.7 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.7 to 5.5			15	
Low level input current	l _{IL} (1)	Ports 0, 1, 2, 3, 7 RES PWM0, PWM1	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			μA
	I _{IL} (2)	XT1, XT2	Input port configuration VIN ^{=V} SS	2.7 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	2.7 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, PWM1	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (5)	P05 to P07	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	(Note 3-1)	I _{OH} =-1mA	2.7 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	.,,
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			0.4	V
	V _{OL} (3)		I _{OL} =2.5mA	2.7 to 5.5			0.4	
	V _{OL} (4)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
	V _{OL} (5)	PWM0, PWM1	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (6)	XT2	I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (7)	Ports 3, 7	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =1mA	2.7 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3, 7	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	1.0
	Rpu(2)			2.7 to 4.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Ports 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		V
Pin capacitance	СР	All pins	For pins other than those under test: VIN ^{=V} SS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

Note 3-1: When the CKO system clock output function (P05) or the audio interface output function (P05 to P07) is used.

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

D	Parameter	Symbol	Pin/	Conditions			Speci	fication	
- Р	rarameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	Frequency	tSCK(1)	SCK0(P12)	See Fig. 9.		2			
	Low level pulse width	tSCKL(1)				1			
	High level	tSCKH(1)				1			
	pulse width	tSCKHA(1a)		 Continuous data transmission/ reception mode USB, AIF, SIO4 not used at the 		4			
ock				same time. • See Fig. 9. • (Note 4-1-2)	-				-
Input clock		tSCKHA(1b)		 Continuous data transmission/ reception mode USB used at the same time AIF, SIO4 not used at the same time. See Fig. 9. (Note 4-1-2) 	2.7 to 5.5	7			tCYC
		tSCKHA(1c)		 Continuous data transmission/ reception mode USB, AIF, SIO4 used at the same time. See Fig. 9. (Note 4-1-2) 		9			
5	Frequency	tSCK(2)	SCK0(P12)	When CMOS output type is		4/3			
	Low level pulse width	tSCKL(2)		selected. • See Fig. 9.			1/2		10.01/
)	High level pulse width	tSCKH(2)					1/2		tSCK
×		tSCKHA(2a)		 Continuous data transmission/ reception mode USB, AIF, SIO4 not used at the same time. When CMOS output type is selected. See Fig. 9. 		tSCKH(2) +2tCYC		tSCKH(2) + (10/3)tCYC	
Output clock		tSCKHA(2b)		 Continuous data transmission/ reception mode USB used at the same time AIF, SIO4 not used at the same time. When CMOS output type is selected. See Fig. 9. 	2.7 to 5.5	tSCKH(2) +2tCYC		tSCKH(2) + (19/3)tCYC	tCY
		tSCKHA(2c)		 Continuous data transmission/ reception mode USB, AIF, SIO4 used at the same time When CMOS output type is selected. See Fig. 9. 		tSCKH(2) +2tCYC		tSCKH(2) + (25/3)tCYC	

Note 4-1-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-1-2: In an application where the serial clock input is to be used in continuous data transmission/reception mode, the time from SIORUN being set when serial clock is high to the falling edge of the first serial clock must be longer than tSCKHA.

Continued on next page.

Cor	ntinu	ed from prec	ceding page.							
	D	arameter	Symbol	Pin/	Conditions		Specification		ication	
	F	arameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Serial input	Dat	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK	0.745.5.5	0.03			
Serial	Dat	ta hold time	thDI(1)		• See Fig. 9.	2.7 to 5.5	0.03			
	Input clock	Output delay time	tdDO(1)	SO0(P10), SB0(P11)	Continuous data transmission/ reception mode (Note 4-1-3)				(1/3)tCYC +0.05	
Serial output	Input		tdDO(2)		Synchronous 8-bit mode (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	μs
Seria	Output clock		tdDO(3)		(Note 4-1-3)				(1/3)tCYC +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be defined as the time up to the beginning of output state change in open drain output mode. See Fig. 9.

	De	arameter	Symbol	Pins/	Conditions			Spec	ification	
	Pa	lameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ĸ	Frequency	tSCK(3)	SCK1(P15)	• See Fig. 9.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			tCYC
Serial clock	Ч	High level pulse width	tSCKH(3)				1			IC YC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	 When CMOS output type is selected. 		2			
	Output clock	Low level pulse width	tSCKL(4)		• See Fig. 9.	2.7 to 5.5		1/2		tSCK
	õ	High level pulse width	tSCKH(4)					1/2		ISCK
Serial input	Da	ta setup time	tsDI(2)	SB1(P14), SI1(P14)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 9. 		0.03			
Serial	Da	ta hold time	thDI(2)			2.7 to 5.5	0.03			
Serial output	Ou tim	tput delay e	tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time up to the beginning of output state change in open drain output mode. See Fig. 9. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

Note 4-2-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

3. SIO4 Serial I/O Characteristics (Note 4-3-1)

	Pa	arameter	Symbol	Pin/	Conditions			Spec	ification	1
		admeter	-	Remarks		V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(5)	SCK4(P24)	See Fig. 9.		2			
		Low level pulse width	tSCKL(5)				1			
		High level	tSCKH(5)				1			
	lock	pulse width	tSCKHA(5a)		 USB, SIO0 continuous transfer mode, AIF not used at the same time. See Fig. 9. (Note 4-3-2) 		4			
	Input clock		tSCKHA(5b)		 USB used at the same time. SIO0 continuous transfer mode, AIF not used at the same time. See Fig. 9. (Note 4-3-2) 	2.7 to 5.5	7			tCYC
			tSCKHA(5c)		 USB, SIO0 continuous transfer mode used at the same time. AIF not used at the same time. See Fig. 9. (Note 4-3-2) 		10			
lock		Frequency	tSCK(6)	SCK4(P24)	When CMOS output type is		4/3			
Serial clock		Low level pulse width	tSCKL(6)		selected. • See Fig. 9.			1/2		tSCK
		High level	tSCKH(6)					1/2		
	ck	pulse width	tSCKHA(6a)		 USB, SIO0 continuous transfer mode AIF not used at the same time. When CMOS output type is selected. See Fig. 9. 		tSCKH(6) + (5/3)tCYC		tSCKH(6) + (10/3)tCYC	
	Output clock		tSCKHA(6b)		 USB used at the same time. SIO0 continuous transfer mode AIF not used at the same time. When CMOS output type is selected. See Fig. 9. 	2.7 to 5.5	tSCKH(6) + (5/3)tCYC		tSCKH(6) + (19/3)tCYC	tCYC
			tSCKHA(6c)		 USB, SIO0 continuous transfer mode used at the same time AIF not used at the same time. When CMOS output type is selected. See Fig. 9. 		tSCKH(6) + (5/3)tCYC		tSCKH(6) + (28/3)tCYC	
input	Dat	ta setup time	tsDI(3)	SO4(P22), SI4(P23)	Must be specified with respect to rising edge of SIOCLK. See Fig. 9.	0.74 5.5	0.03			
Serial input	Dat	ta hold time	thDI(3)			2.7 to 5.5	0.03			
Serial output	Our	tput delay e	tdDO(5)	SO4(P22), SI4(P23)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time up to the beginning of output state change in open drain output mode See Fig. 9. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

Note 4-3-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-3-2: In an application where the serial clock input is to be used, the time from SI4RUN being set when serial clock is high to the falling edge of the first serial clock must be longer than tSCKHA when continuous data transmission/reception is started.

T 1					cteristics (Note 4-4-1)	1		Speci	ification	
	Pa	arameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(7)	SM0CK0(P17),	See Fig. 9.		4/3			
	Input clock	Low level pulse width	tSCKL(7)	SM0CK1(P13)		2.7 to 5.5	2/3			
Serial clock	Inpu	High level pulse width	tSCKH(7)				2/3			tCYC
erial	×	Frequency	tSCK(8)	SM0CK0(P17),	When CMOS output type is		4/3			
Ñ	Output clock	Low level pulse width	tSCKL(8)	SM0CK1(P13)	selected. • See Fig. 9.	2.7 to 5.5		1/2		
	Outp	High level pulse width	()				1/2			tSCK
input	Da	ta setup time	tsDI(4)	SM0DA0(P16), SM0DA1(P14)	Must be specified with respect to rising edge of SIOCLK.		0.03			
Serial input	Da	ta hold time	thDI(4)		• See Fig. 9.	2.7 to 5.5	0.03			
Serial output	Ou tim	itput delay ie	tdDO(6)	SM0DO(P15), SM0DA0(P16), SM0DA1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change. See Fig. 9. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

Note 4-4-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

4-2. SMIIC0 I²C Mode I/O Characteristics (Note 4-5-1)

	I	Parameter		Symbol	Pin/Remarks	Conditions	-		Speci	fication	
				Cymbol	1 min contanto		V _{DD} [V]	min	typ	max	unit
	ock	Frequency Low level		tSCL tSCLL	SM0CK0(P17), SM0CK1(P13)	See Fig. 11.		5			
×	Input clock	pulse width High level		tSCLH			2.7 to 5.5	2.5			Tfilt
Serial clock		pulse width						2			
Seri	ъс	Frequency Low level		tSCLx tSCLLx	SM0CK0(P17), SM0CK1(P13)	Must be specified as the time up to the beginning of output state		10			
	Output clock	pulse width Highlevel		tSCLHx		change.	2.7 to 5.5		1/2		tSCL
~		pulse width							1/2	1	
	out sp	K, SM0DA pin pike suppressi	on	tsp	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16), SM0DA1(P14)	See Fig. 11.	2.7 to 5.5			1	Tfilt
	twee	inquish time en start and	input	tBUF	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16), SM0DA1(P14)	See Fig. 11.		2.5			Tfilt
			Output	tBUFx		Standard clock mode Must be specified as the time up to the beginning of output state change.	2.7 to 5.5	5.5			
			Out			 High-speed clock mode Must be specified as the time up to the beginning of output state change. 		1.6			μs
		estart on hold time	input	tHD; STA	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16),	When SMIIC register control bit SHDS=0 See Fig. 11.		2.0			Tfilt
			. <u>E</u>		SM0DA1(P14)	When SMIIC register control bit SHDS=1 See Fig. 11.		2.5			
			Output	tHD; STAx		Standard clock mode Must be specified as the time up to the beginning of output state change.	2.7 to 5.5	4.1			
			лО			High-speed clock mode Must be specified as the time up to the beginning of output state change.		1.0			μs
	estart tup ti	t condition ime	input	tSU; STA	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16), SM0DA1(P14)	See Fig. 11.		1.0			Tfilt
			Output	tSU; STAx		Standard clock mode Must be specified as the time up to the beginning of output state change.	2.7 to 5.5	5.5			
			Out			 High-speed clock mode Must be specified as the time up to the beginning of output state change. 		1.6			μs

Continued on next page.

Deremeter		Oursels al	Dia (Descender	Quaditions		:	Specific	ation	
Parameter		Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Stop condition setup time	input	tSU; STO	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16),	See Fig. 11.		1.0			Tfilt
	Output	tSU; STOx	SM0DA1(P14)	 Standard clock mode Must be specified as the time up to the beginning of output state change. 	2.7 to 5.5	4.9			
	Out			 High-speed clock mode Must be specified as the time up to the beginning of output state change. 		1.1			μs
Data hold time	Input	tHD; DAT	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16),	See Fig. 11.		0			
	Output	tHD; DATx	SM0DA1(P14)	Must be specified as the time up to the beginning of output state change.	2.7 to 5.5	1		1.5	Tfilt
Data setup time	Input	tSU; DAT	SM0CK0(P17), SM0CK1(P13), SM0DA0(P16),	See Fig. 11.		1			
	Output	tSU; DATx	SM0DA1(P14)	Must be specified as the time up to the beginning of output state change.	- 2.7 to 5.5 -	1tSCL- 1.5Tfilt			- Tfilt

Note 4-5-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-5-2: The value of Tfilt is determined by bits 7 and 6 (BRP1 and BRP0) of the SMIC0BRG register and the system clock frequency.

BRP1	BRP0	Tfilt
0	0	(1/3) tCYC×1
0	1	(1/3) tCYC×2
1	0	(1/3) tCYC×3
1	1	(1/3) tCYC×4

Set the value of the BRP1 and BRP0 bits so that the value of Tfilt falls within the following value range: $250ns \ge Tfilt > 140ns$

Note 4-5-3: For standard clock mode operation, set up the SMIC0BRG register so that the following conditions are satisfied:

 $250ns \geq Tfilt > 140ns$

BRDQ (bit5) = 1

SCL frequency value ≤ 100 kHz

For high-speed clock mode operation, set up the SMIC0BRG register so that the following conditions are satisfied:

 $250 \text{ns} \ge \text{Tfilt} > 140 \text{ns}$ BRDQ (bit5) = 1 SCL frequency value $\le 400 \text{kHz}$

Parameter	Cumbal	Pin/Remarks	Conditions			Spe	cification	
Parameter	Symbol	Pill/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level	tPIH(1)	INT0(P70),	Interrupt source flag can be					
pulse width	tPIL(1)	INT1(P71),	set.					
		INT2(P72),	Event inputs for timer 0/1 are					
		INT4(P20 to P23),	enabled.	2.7 to 5.5	1			
		INT5(P24 to P25),						
		INT6(P20),						
		INT7(P24)						
	tPIH(2)	INT3(P73) when	Interrupt source flag can be					
	tPIL(2)	noisefilter time constant	set.	2.7 to 5.5	2			
		is 1/1.	Event inputs for timer 0 are	2.7 10 5.5	2			tCYC
			enabled.					
	tPIH(3)	INT3(P73) when	Interrupt source flag can be					
	tPIL(3)	noisefilter time constant	set.	2.7 to 5.5	64			
		is 1/32.	Event inputs for timer 0 are	2.7 10 5.5	04			
			enabled.					
	tPIH(4)	INT3(P73) when	Interrupt source flag can be					
	tPIL(4)	noisefilter time constant	set.		256			
		is 1/128.	Event inputs for timer 0 are	2.7 to 5.5	200			
			enabled.					
	tPIL(5)	RMIN(P73)	Recognized as a signal by					RMCK
			infrared remote control	2.7 to 5.5	4			-
			receiver circuit					(Note 5-1
	tPIL(6)	RES	Resetting is enabled.	2.7 to 5.5	200			μs

Pulse Input Conditions at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

Note 5-1: Denotes the reference frequency of the infrared remote control receiver circuit (1tCYC to 128tCYC or source oscillation frequency of the subclock)

AD Converter Characteristics at Ta = -40°C to +85°C, $V_{SS1} = V_{SS2} = V_{SS3} = 0V$

<12-bit AD Converter Mode>

Deservator	Symbol Pin/Remarks		Quadiliana			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00)		3.0 to 5.5		12		bit
Absolute accuracy	ET	to AN7(P07)	(Note 6-1)	3.0 to 5.5			±16	LSB
Conversion time	TCAD	AN8(P70) AN9(P71)	See conversion time	4.0 to 5.5	32		115	
		AN10(XT1)	calculation formulas. (Note 6-2)	3.0 to 5.5	64		115	μs
Analog input voltage range	VAIN	AN11(XT2)		3.0 to 5.5	V _{SS}		V _{DD}	V
Analog port input	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μA

<8-bit AD Converter Mode>

Deservator	Symbol Pin/Remarks		Conditions			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00)		3.0 to 5.5		8		bit
Absolute accuracy	ET	to AN7(P07)	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN8(P70) AN9(P71)	See conversion time	4.0 to 5.5	20		90	
		AN10(XT1)	calculation formulas. (Note 6-2)	3.0 to 5.5	40		90	μs
Analog input voltage range	VAIN	AN11(XT2)		3.0 to 5.5	V _{SS}		V _{DD}	V
A Analog port input	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μA

Conversion time calculation formulas :

12-bits AD Converter Mode : TCAD (Conversion time) = $((52/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$ 8-bits AD Converter Mode : TCAD (Conversion time) = $((32/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$

<Recommended Operating Conditions>

External	Supply Voltage	System Clock	Cycle Time	AD Frequency	Conversion Tir	me (TCAD)[μs]
Oscillator	Range	Division	tCYC [ns]	Division Ratio	12-bit AD	8-bit AD
FmCF[MHz]	V _{DD} [V]	(SYSDIV)		(ADDIV)		
12	4.0 to 5.5	1/1	250	1/8	34.8	21.5
	3.0 to 5.5	1/1	250	1/16	69.5	42.8

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process until the time the conversion result register is loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is doubled in the following cases:

• The AD conversion is carried out in the 12-bit AD conversion mode for the first time after a system reset.

• The AD conversion is carried out for the first time after the AD conversion mode is switched from 8-bit to 12-bit AD conversion mode.

				Specification					
Parameter	Symbol	Conditions	Option selected voltage	min	typ	max	unit		
POR release voltage	PORRL	Select from option (Note 7-1)	1.67V	1.55	1.67	1.79			
			1.97V	1.85	1.97	2.09			
			2.07V	1.95	2.07	2.19			
			2.37V	2.25	2.37	2.49	V		
			2.57V	2.45	2.57	2.69			
			2.87V	2.75	2.87	2.99			
			3.86V	3.73	3.86	3.99			
			4.35V	4.21	4.35	4.49			
Detection voltage Inknown state	POUKS	See Fig. 13 (Note 7-2)			0.7	0.95			
Power supply rise ime	PORIS	Power supply rise time from VDD=0V to 1.6V				100	ms		

Note 7-1: The POR release level can be selected out of 8 levels only when LDV reset function is disabled. Note 7-2: POR is in unknown state before transistors start operation.

Low Voltage Detection (LVD) Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

					Specifica	tion	
Parameter	Symbol	Conditions	Option selected voltage	min	typ	max	unit
LVD reset voltage	LVDET	Select from option.	1.91V	1.81	1.91	2.01	
(Note 8-2)		See Fig. 14.	2.01V	1.91	2.01	2.11	
		(Note 8-1) (Note 8-3)	2.31V	2.21	2.31	2.41	
			2.51V	2.41	2.51	2.61	V
			2.81V	2.71	2.81	2.91	
			3.79V	3.69	3.79	3.89	
			4.28V	4.18	4.28	4.38	
LVD hysteresis width	LVHYS	LVHYS	1.91V		55		mV
			2.01V		55		
			2.31V		55		
			2.51V		55		
			2.81V		55		
			3.79V		60		
			4.28V		65		
Detection voltage unknown state	LVUKS	See Fig. 14. (Note 8-4)			0.7	0.95	V
Low voltage detection minimum width (Reply sensitivity)	TLVDW	LVDET-0.5V See Fig. 15.		0.2			ms

Note 8-1: The LVD reset level can be selected out of 7 levels only when the LVD reset function is enabled.

Note 8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note 8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note 8-4: LVD is in an unknown state before transistors start operation.

Consumptio	on Current C		ristics at Ta = -40° C to $+85^{\circ}$ C, V _{SS} 1 =	$V_{SS2} = V_S$	$S^3 = 0$			
Parameter	Symbol	Pin/	Conditions			Specifi		
Normal mode consumption current	IDDOP(1)	Remarks V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	V _{DD} [V] 4.5 to 5.5	min	typ 9.8	max 18	unit
(Note 9-1) (Note 9-2)	IDDOP(2)	-	Internal PLL oscillation stopped Internal low-/medium-speed RC oscillation stopped USB circuit stopped 1/1 frequency division ratio FmCF=12MHz ceramic oscillation mode	3.0 to 3.6		5.7	11	
			FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal PLL oscillation mode active	4.5 to 5.5		15	28	
			 Internal low-/medium-speed RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		8.1	15	mA
	IDDOP(3)		FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		6.7	12	
			 System clock set to 6MHz side Internal low-/medium-speed RC oscillation 	3.0 to 3.6		4.2	7.1	
			stopped 1/2 frequency division ratio 	2.7 to 3.0		3.5	5.8	
	IDDOP(4)		External oscillation FmCF stopped FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		0.77	2.8	
			 System clock set to internal medium-speed RC oscillation 	3.0 to 3.6		0.46	1.5	
			 Internal low-speed RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		0.39	1.3	
	IDDOP(5)		 External oscillation FsX'tal /FmCF stopped System clock set to internal low-speed RC 	4.5 to 5.5		28	170	-
			oscillation Internal medium-speed RC oscillation stopped 	3.0 to 3.6		18	100	-
		-	1/1 frequency division ratio	2.7 to 3.0		16	87	-
	IDDOP(6)		 External oscillation FmCF stopped FsX'tal=32.768kHz crystal oscillation mode 	4.5 to 5.5		45	124	μA
			 System clock set to 32.768kHz side Internal low-/medium-speed RC oscillation 	3.0 to 3.6		18	60	
			stopped 1/2 frequency division ratio 	2.7 to 3.0		14	48	
HALT mode consumption current (Note 9-1)	IDDHALT(1)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		4.0	7.0	
(Note 9-2)			 Internal PLL oscillation stopped Internal low-/medium-speed RC oscillation stopped USB circuit stopped 1/1 frequency division ratio 	3.0 to 3.6		2.2	3.8	mA

Note 9-1: The consumption current value do not include current that flows into the output transistors and internal pull-up resistors.

Note 9-2: The consumption current values do not include operational current of LVD (Low Voltage Detection) function if not specified.

Continued on next page.

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Parameter	Symbol	Pin/	Conditions			Specifi	ication	1
T didificter	Gymbol	Remarks		V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 9-1) (Note 9-2)	IDDHALT(2)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal PLL oscillation active	4.5 to 5.5		9.2	18	
			 Internal low-/medium-speed RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		4.7	8.6	
	IDDHALT(3)		HALT mode FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		2.5	4.5	
			 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side Internal low-/medium-speed RC oscillation 	3.0 to 3.6		1.3	2.3	mA
			stopped • 1/2 frequency division ratio	2.7 to 3.0		1.1	1.8	
	IDDHALT(4)		HALT mode External oscillation FmCF stopped Solution FmCF stopped	4.5 to 5.5		0.41	1.5	
			 FsX'tal=32.768kHz crystal oscillation mode System clock set to internal medium-speed RC oscillation 	3.0 to 3.6		0.20	0.72	
			Internal low-speed RC oscillation stopped I/2 frequency division ratio	2.7 to 3.0		0.17	0.53	
	IDDHALT(5)		HALT mode External oscillation FsX'tal /FmCF stopped	4.5 to 5.5		7.2	95	
			 System clock set to internal low-speed RC oscillation 	3.0 to 3.6		4.0	51	
			Internal medium-speed RC oscillation stopped. 1/1 frequency division ratio	2.7 to 3.0		3.4	43	
	IDDHALT(6)		HALT mode External oscillation FmCF stopped	4.5 to 5.5		30	112	
			 FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal low-/medium-speed RC oscillation 	3.0 to 3.6		8.4	51	
			stopped. 1/2 frequency division ratio 	2.7 to 3.0		5.8	40	
HOLD mode	IDDHOLD(1)		HOLD mode	4.5 to 5.5		0.28	67	
consumption			• CF1=V _{DD} or open	3.0 to 3.6		0.22	35	
current (Note 9-1)			(External clock mode)	2.7 to 3.0		0.21	30	
(Note 9-2)	IDDHOLD(2)		HOLD mode	4.5 to 5.5		2.8	70	μA
, ,			LVD option selected	3.0 to 3.6		2.3	38	
			CF1=V _{DD} or open (External cleark mode)	2.7 to 3.0		2.1	33	
	IDDHOLD(3)		(External clock mode) • HOLD mode	4.5 to 5.5		0.98	68	
			 Internal timer type watchdog timer active (Internal low-speed RC oscillation circuit active) 	3.0 to 3.6		0.62	36	
			CF1=V _{DD} or open (External clock mode)	2.7 to 3.0		0.51	31	
X'tal HOLD	IDDHOLD(4)		X'tal HOLD mode	4.5 to 5.5		26	106	
mode			• CF1=V _{DD} or open	3.0 to 3.6		6.1	49	
consumption			(External clock mode)				_	
current			FsX'tal=32.768kHz crystal oscillation mode	2.7 to 3.0		3.8	38	
(Note 9-1) (Note 9-2)	IDDHOLD(5)		 X'tal HOLD mode CF1=V_{DD} or open 	4.5 to 5.5		1.0	68	
			(External clock mode) • FmSRC=30kHz internal low-speed RC oscillation	3.0 to 3.6		0.64	36	
			mode	2.7 to 3.0		0.53	31	

Note 9-1: The consumption current value do not include current that flows into the output transistors and internal pull-up resistors.

Note 9-2: The consumption current values do not include operational current of LVD (Low Voltage Detection) function if not specified.

USB Characteristics and Timing at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Deventer	Symbol Pin/Remarks			Conditions					
Parameter			min	typ	max	unit			
High level output	V _{OH(USB)}	• 15kΩ±5% to GND	2.8		3.6	V			
Low level output	VOL(USB)	• 1.5kΩ±5% to 3.6V	0.0		0.3	V			
Output signal crossover voltage	V _{CRS}		1.3		2.0	V			
Differential input sensitivity	V _{DI}	• (UHAD+) – (UHAD–) • (UHBD+) – (UHBD–)	0.2			V			
Differential input common mode range	V _{CM}		0.8		2.5	V			
High level input	V _{IH(USB)}		2.0		3.6	V			
Low level input	V _{IL(USB)}		0.0		0.8	V			
Rise time (full-speed)	t _{FR}	R _S =33Ω, C _L =50pF	4		20	ns			
Fall time (full-speed)	tFF	R _S =33Ω, C _L =50pF	4		20	ns			
Rise time (low-speed)	^t LR	R_S =33 Ω , CL=200 to 600pF	75		300	ns			
Fall time (low-speed)	t _{LF}	$R_S=33\Omega$, $C_L=200$ to 600pF	75		300	ns			

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symphol	Pin/Remarks	Conditions		Specification			
Farameter	Parameter Symbol Pin/Remarks Conditions		V _{DD} [V]	min	typ	max	unit	
Onboard programming current	IDDFW(1)	V _{DD} 1	Excluding power dissipation in the microcontroller block	3.0 to 5.5		5	10	mA
Programming time	tFW(1)		 Erase operation 	3.0 to 5.5		20	30	ms
	tFW(2)		Write operation	3.0 10 5.5		40	60	μs

Main System Clock Oscillation

The characteristics of a sample main system clock oscillator circuit shown in Table 1 are measured using a Our specification oscillation characteristics evaluation board and external components with circuit constant values with which the resonator vendor confirmed normal and stable oscillation.

Table 1 shows the characteristics of a oscillator circuit when USB host function is not used. If USB host function is to be used, it is absolutely recommended to use a resonator that satisfies the precision and stability according to the USB standards (±500ppm)

Nominal	Manada a Niana a		Circuit Constant			Operating Voltage	Oscillation Stabilization Time		Develo
Frequency	Vendor Name	Resonator Name	C1	C2	Rd1	Range	typ	max	Remarks
			[pF]	[pF]	[Ω]	[V]	[ms]	[ms]	
									C1 and C2
12MHz	MURATA	CSTCE12M0GH5L**-R0	(33)	(33)	470	3.0 to 5.5	0.1	0.5	integrated
									SMD type

The oscillation stabilization time is required for the oscillator to get stabilized in the following cases (see Figure 4):

- Until oscillation is stabilized after VDD goes above the operating voltage lower limit
- Until oscillation is stabilized after the instruction for starting the main clock oscillator circuit is executed
- Until oscillation is stabilized after HOLD mode is released.
- Until oscillation is stabilized after X'tal HOLD mode is released with CFSTOP (OCR register, bit 0) set to 0 and oscillation is started.

Subsystem Clock Oscillation

Table 2 shows the characteristics of a sample subsystem clock oscillator circuit that are measured using a Our specification oscillation characteristics evaluation board and external components with circuit constant values with which the resonator vendor confirmed normal and stable oscillation.

Table 2	Characteristics of	f a Sample Subsystem	Clock Oscillator	Circuit with a Crystal Resonator
10010 -	Characterioutes of			

	Nominal Frequency	Vendor Name	Resonator Name	Circuit Constant				Operating Voltage	Oscillation Stabilization Time		Devedo
				C3 [pF]	C4 [pF]	Rf [Ω]	Rd2 [Ω]	Range [V]	typ [s]	max [s]	Remarks
	32.768kHz	EPSON TOYOCOM	MC-306	18	18	Open	680k	2.7 to 5.5	1.1	3.0	Applicable CL value=12.5pF SMD type

The oscillation stabilization time is required for the oscillator to get stabilized in the following cases (see Figure 4):

Until oscillation is stabilized after the instruction for starting the subclock oscillator circuit is executed
Until oscillation is stabilized after HOLD mode is released with EXTOSC (OCR register, bit 6) set to 1 and oscillation is started.

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.



Figure 1 CF Oscillator Circuit



Figure 2 Crystal Oscillator Circuit





Figure 4 Oscillation Stabilization Time



When using the internal PLL circuit to generate the 48MHz clock for USB, it is necessary to connect a filter circuit as shown in the left figure to the P34/UFILT pin. After PLL is set, stabilization time of 20ms or longer must be secured.





To generate the master clock for the audio interface using the internal PLL circuit, it is necessary to connect a filter circuit as shown in the left figure to the P33 pin.

Figure 6 External Filter Circuit for Audio Interface (Used with Internal PLL Circuit)



It is necessary to adjust the circuit constant of the USB port peripheral circuit for each mounting board.





Note:

The external circuit differs depending on which of the power-on reset and low-voltage reset functions is to be used. Refer to the section on the reset functions in the user's manual.















Figure 12 USB Data Signal Timing and Voltage Levels



Figure 13 Sample Waveforms for POR-only (LVD deselected) Operation (Reset pin: Pull-up resistor PRES only)

- The POR function generates a reset only when the power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again if the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function as explained below or implement an external reset circuit.
- A reset is generated only when power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.



Figure 14 Sample Waveforms for POR+LVD Operation (Reset pin: Pull-up Resistor PRES Only)

- A reset is generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent repetitions of reset release and entry cycles near the detection level.



Figure 15 Minimum Low Voltage Detection Width (Sample Temporary Power Interruption/Fluctuation Waveform)

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)		
LC87F1K64AUWA-2H	SQFP48(7X7) (Pb-Free / Halogen Free)	250 / Tray Foam		

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